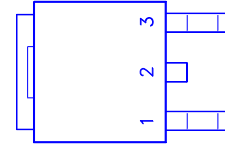
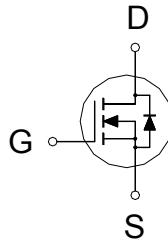


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
25V	20mΩ	32A



- 1. GATE
- 2. DRAIN
- 3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	25	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	$T_C = 25\text{ °C}$	I_D	32	A
	$T_C = 100\text{ °C}$		20	
Pulsed Drain Current ¹		I_{DM}	110	
Avalanche Current		I_{AS}	23	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	27	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	35	W
	$T_C = 100\text{ °C}$		14	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		3.6	°C / W
Junction-to-Ambient	$R_{\theta JA}$		75	
Case-to-Heatsink	$R_{\theta CS}$	0.7		

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ °C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	25			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.8	2.5	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			±250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V$			25	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 125\text{ °C}$			250	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 10V, V_{GS} = 10V$	110			A

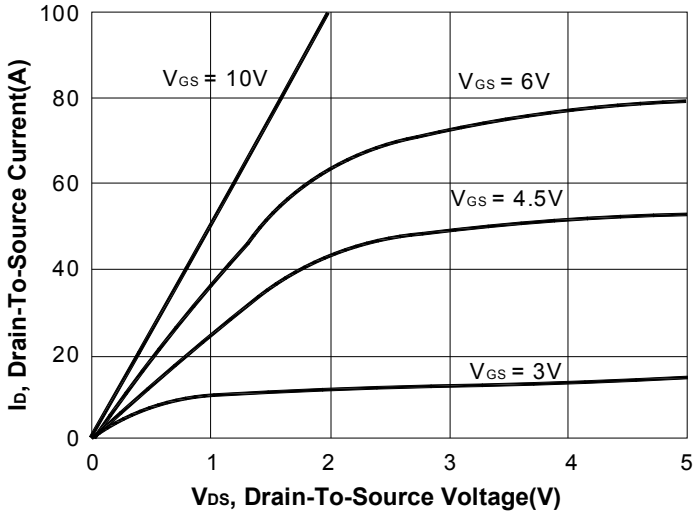
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$	29	41	mΩ
		$V_{GS} = 10V, I_D = 15A$	14	20	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 15A$	19		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$	492		pF
Output Capacitance	C_{oss}		221		
Reverse Transfer Capacitance	C_{rss}		187		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	1.5		Ω
Total Gate Charge ²	$Q_g(V_{GS}=10V)$	$V_{DS} = 15V, I_D = 15A$	14.7		nC
	$Q_g(V_{GS}=4.5V)$		7.7		
Gate-Source Charge ²	Q_{gs}		2.3		
Gate-Drain Charge ²	Q_{gd}		5.6		
Turn-On Delay Time ²	$t_{d(on)}$		$V_{DD} = 15V$ $I_D \cong 15A, V_{GS} = 10V, R_{GS} = 6\Omega$	10	
Rise Time ²	t_r	17			
Turn-Off Delay Time ²	$t_{d(off)}$	34			
Fall Time ²	t_f	27			
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_C = 25 °C)					
Continuous Current	I_S			25	A
Forward Voltage ¹	V_{SD}	$I_F = 15A, V_{GS} = 0V$		1.4	V
Reverse Recovery Time	t_{rr}	$I_F = 15A, di_F/dt = 100A / \mu S$	27		nS
Reverse Recovery Charge	Q_{rr}		36		nC

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

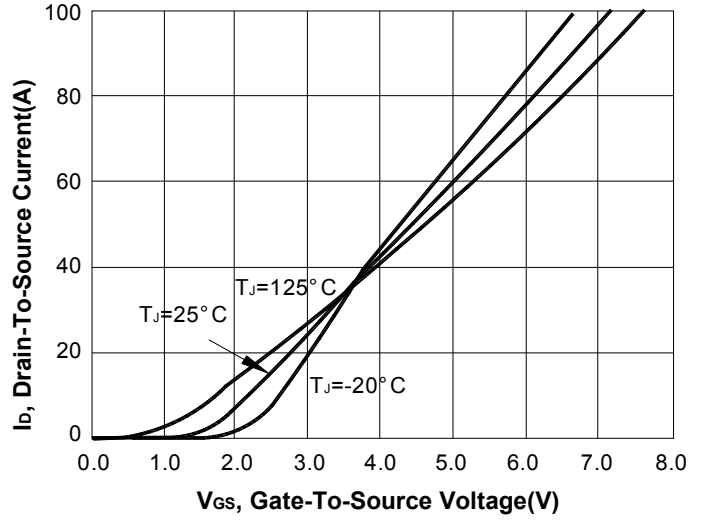
²Independent of operating temperature.

REMARK: THE PRODUCT MARKED WITH "P2003BDG", DATE CODE or LOT #

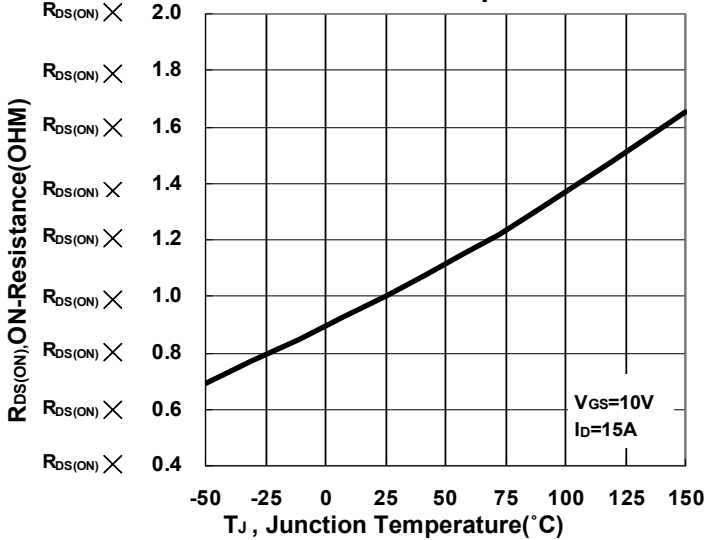
Output Characteristics



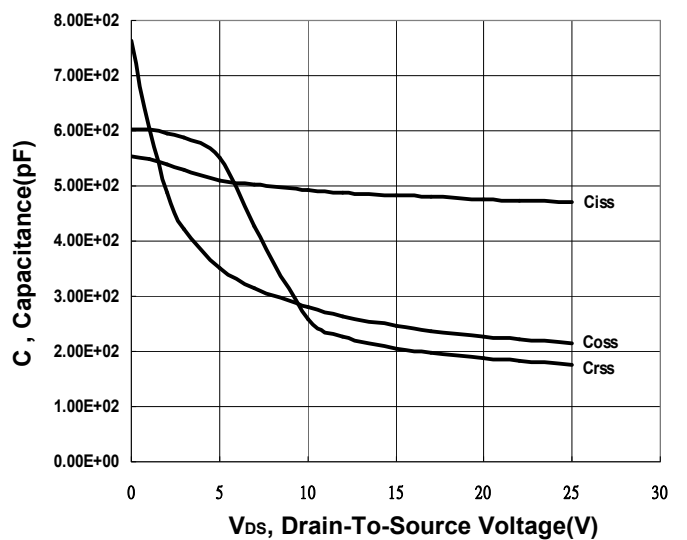
Transfer Characteristics



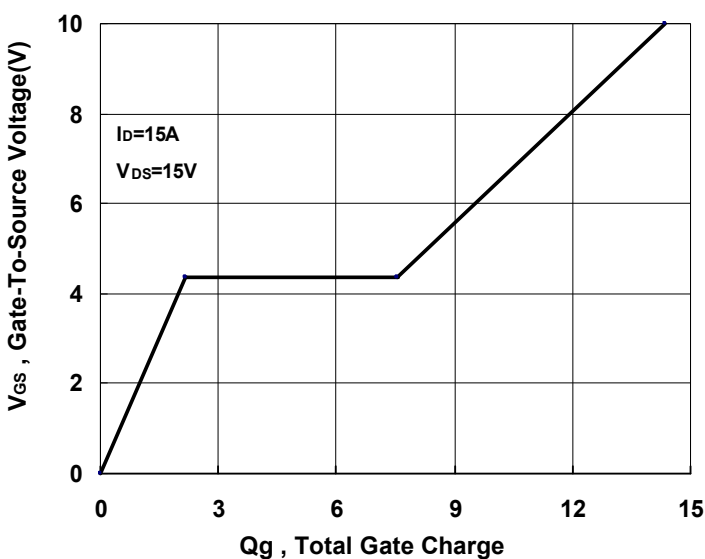
On-Resistance VS Temperature



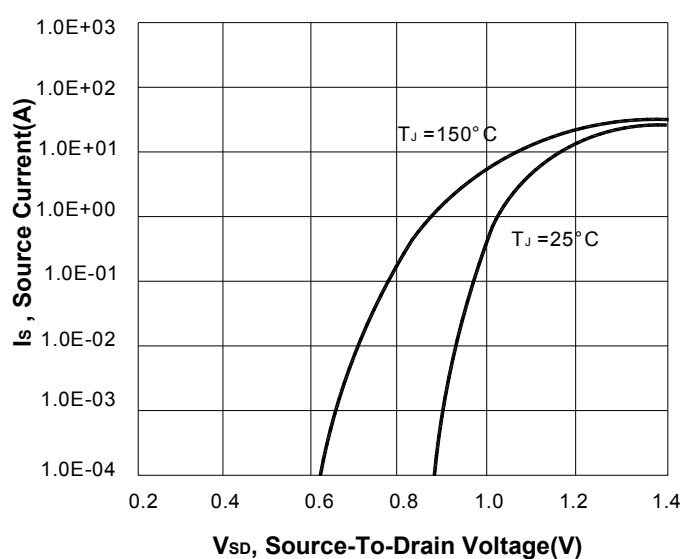
Capacitance Characteristic



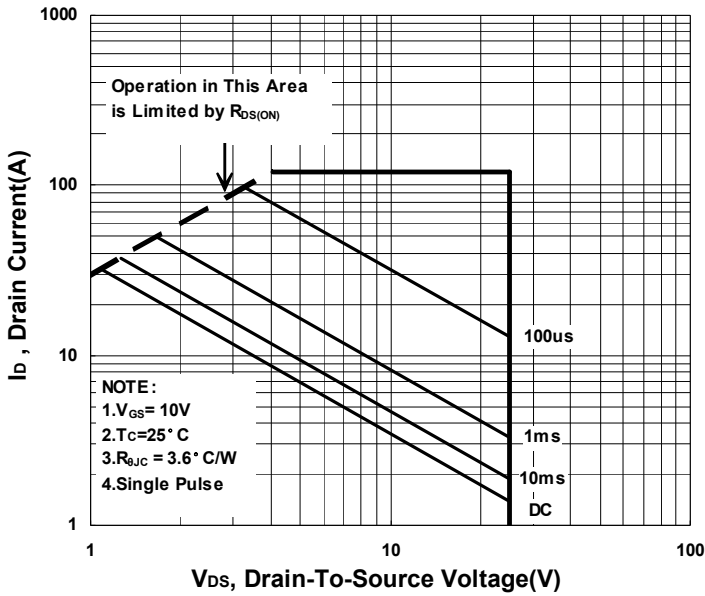
Gate charge Characteristics



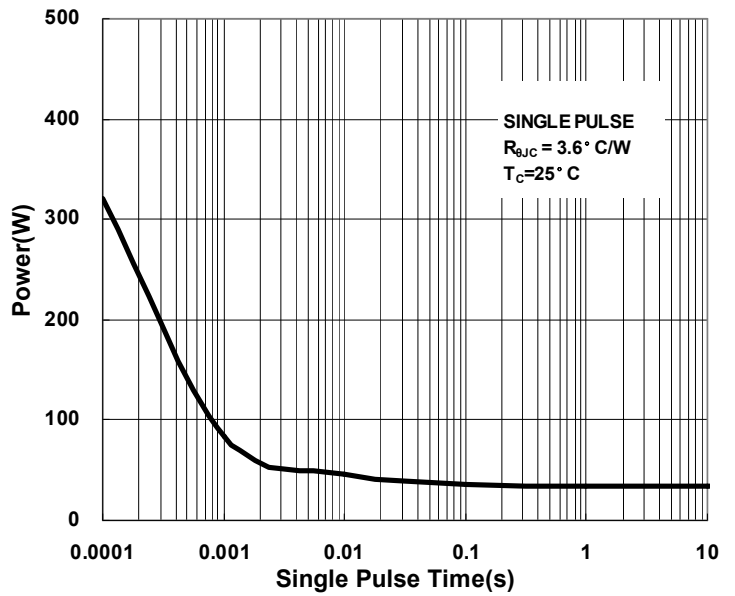
Source-Drain Diode Forward Voltage



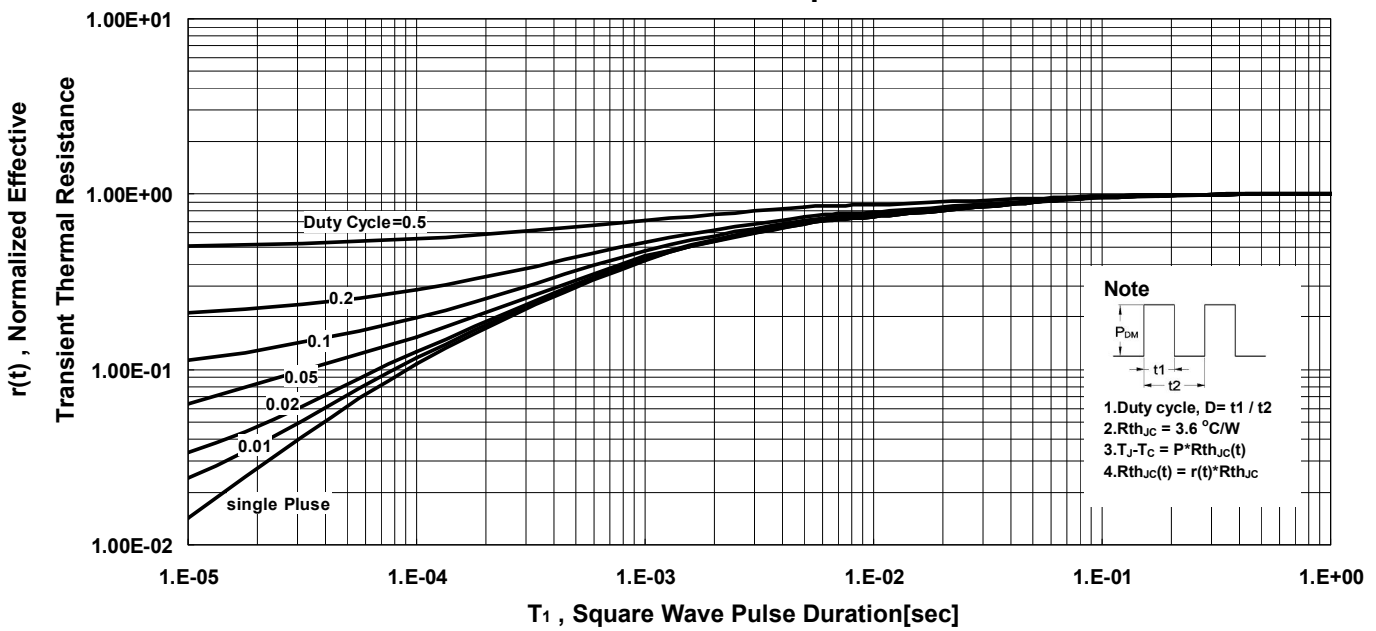
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



TO-252 (DPAK) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	9.5	10.4	H	0.8	1.27	2.03
B	2.19	2.3	2.435	I	6.35	6.6	6.8
C	0.35	0.5	0.65	J	4.8	5.34	5.5
D	0.89		1.5	K	0.5		1.5
E	0.35		0.65	L	0.4	0.76	0.89
F	0.0		0.23	M	3.96		5.18
G	5.4		6.2	W	3.38	3.58	3.78

